

Appendix

Changes to the current claims.

Please cancel claim 20 and amend claims 1, 12, and 21 as follows:

1. (Amended) A method of forming a semiconductor structure, comprising:
forming an isolation region in a semiconductor substrate; wherein
a first oxide layer is on said substrate,
a first sacrificial layer is on said first oxide layer, wherein said first
sacrificial layer comprises an oxide, and
a first nitride layer is on said first sacrificial layer.
12. (Amended) A method of forming a semiconductor structure, comprising:
removing a first nitride layer and a first sacrificial layer, wherein said first
sacrificial layer comprises an oxide;
wherein a first oxide layer is on a substrate,
said first sacrificial layer is on said first oxide layer, and
said first nitride layer is on said first sacrificial layer.
20. ~~In a method of forming an isolation region in a semiconductor device, including forming an isolation nitride on a substrate, the improvement comprising forming a first sacrificial layer between said isolation nitride and said substrate.~~
21. (Amended) ~~In a method of forming an isolation region in a semiconductor device, including forming an isolation nitride on a substrate, the improvement comprising forming a first sacrificial layer between said isolation nitride and said substrate and~~ The method of claim 20, further comprising forming a second sacrificial layer between said first sacrificial layer and said substrate.